

MECHANICAL CASE OUTLINE

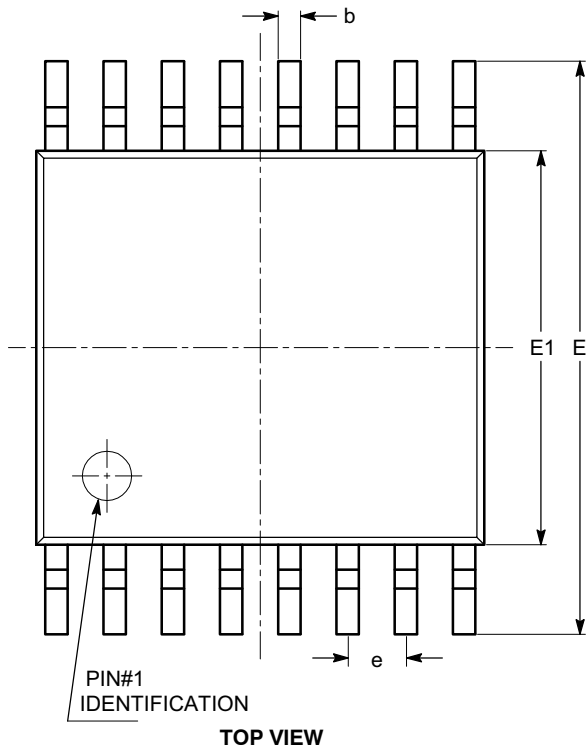
PACKAGE DIMENSIONS

ON Semiconductor®

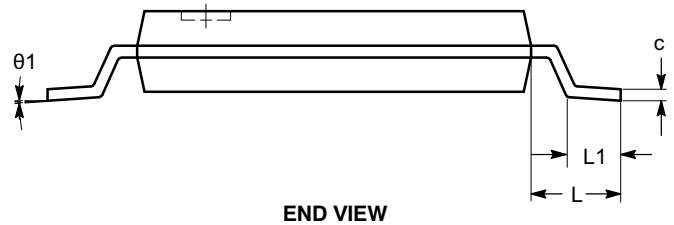
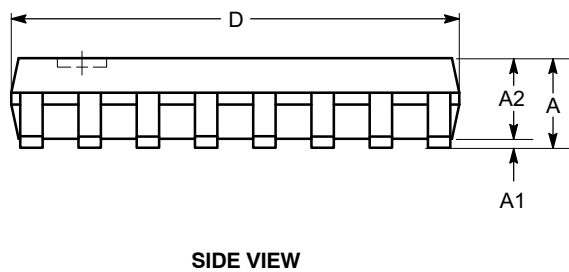


TSSOP16, 4.4x5
CASE 948AN-01
ISSUE O

DATE 19 DEC 2008



SYMBOL	MIN	NOM	MAX
A			1.10
A1	0.05		0.15
A2	0.85		0.95
b	0.19		0.30
c	0.13		0.20
D	4.90		5.10
E	6.30		6.50
E1	4.30		4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.45		0.75
θ	0°		8°



Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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DESCRIPTION:	TSSOP16, 4.4X5	PAGE 1 OF 2

